

RCJ120N20

Nch 200V 12A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	325m $Ω$
I _D	±12A
P_D	52W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

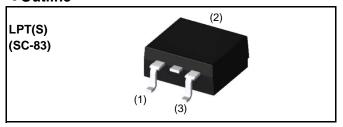
Application

Switching Power Supply

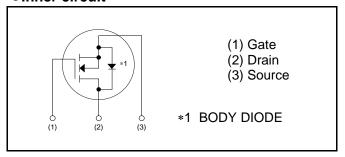
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	24
Туре	Basic ordering unit (pcs)	1,000
	Taping code	TL
	Marking	RCJ120N20

• Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	200	V	
Ocation and desire assessed	T _c = 25°C	I _D *1	±12	А
Continuous drain current	T _c = 100°C	I _D *1	±6.5	А
Pulsed drain current		I _{D,pulse} *2	±48	А
Gate - Source voltage		V_{GSS}	±30	V
Avalanche energy, single pulse		E _{AS} *3	11.6	mJ
Avalanche current		I _{AR} *3	6.0	А
$T_c = 25^{\circ}C$		P _D	52	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.56	W
Junction temperature	T _j	150	°C	
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	2.36	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	V
		$V_{DS} = 200V, V_{GS} = 0V$	_	_	10	
Zero gate voltage drain current	lana	$T_j = 25^{\circ}C$	_	-	10	μΑ
Zero gate voltage drain current		$V_{DS} = 200V, V_{GS} = 0V$	-	-	100	
		T _j = 125°C				
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	ı	ı	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V$, $I_D = 1mA$	3.25	•	5.25	V
		$V_{GS} = 10V, I_D = 6.0A$	-	250	325	
Static drain - source on - state resistance	$R_{DS(on)}^{}^{*5}}$	$V_{GS} = 10V, I_D = 6.0A$	_	565	790	mΩ
		T _j = 125°C	_	303	130	
Forward transfer admittance	g_{fs}	$V_{DS} = 10V, I_{D} = 6.0A$	2.75	5.50	-	S

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	740	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	57	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	26	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 100 V$, $V_{GS} = 10 V$	-	20	-	
Rise time	t _r *5	$I_{D} = 6.0A$	-	33	-	nc
Turn - off delay time	t _{d(off)} *5	$R_L = 16.67\Omega$	-	27	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	11	-	

● Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 100V	-	15	-	
Gate - Source charge	Q _{gs} *5	I _D = 12A	-	6	-	nC
Gate - Drain charge	${\sf Q_{gd}}^{*5}$	V _{GS} = 10V	-	6	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 100V$, $I_D = 12A$	-	7.4	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol Conditions		Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	ı	12	Α
Pulsed source current	I _{SM} *2	1 _c = 23 0	-	-	48	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 12A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 6.0A	-	80	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	30	-	nC

^{*1} Limited only by maximum temperature allowed.

*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

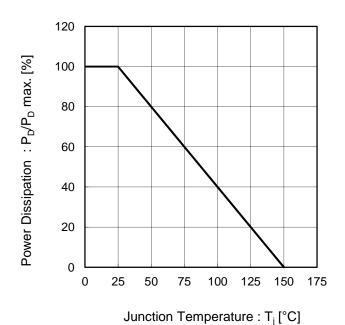
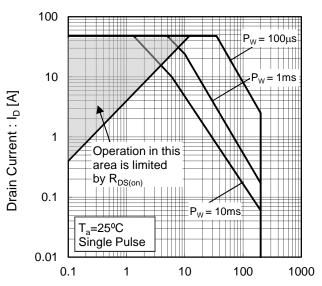
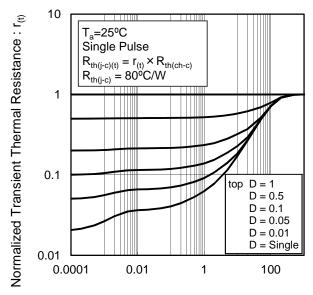


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

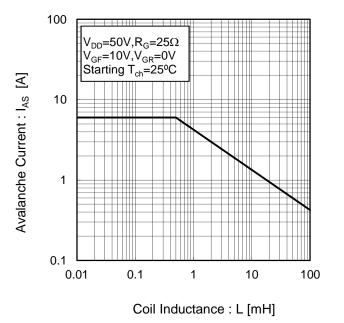
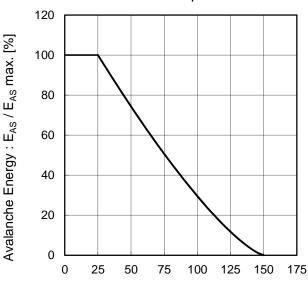
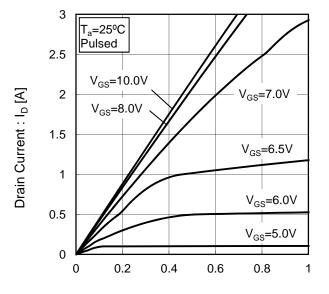


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



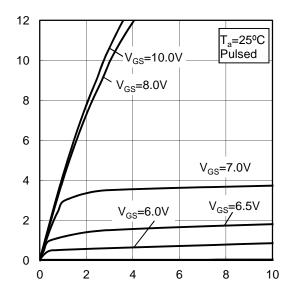
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1 \text{mA}$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature

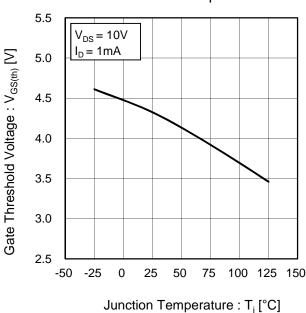
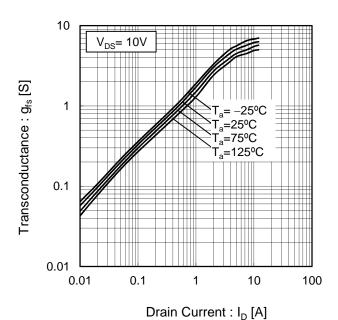


Fig.11 Transconductance vs. Drain Current

Gate - Source Voltage : V_{GS} [V]





Resistance vs. Gate Source Voltage 800 T_a=25°C Static Drain - Source On-State Resistance Static Drain - Source On-State Resistance 700 600 $I_D = 6A$ I_D = 12A 500 $:R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ $: R_{\text{DS(on)}} \left[\text{m}\Omega\right]$ 400 300 200 100 0 0 5 10 15 20

Fig.12 Static Drain - Source On - State

Drain Current : I_D [A]

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

Junction Temperature : T_j [°C]

Gate - Source Voltage : V_{GS} [V]

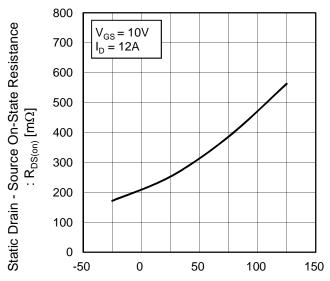


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

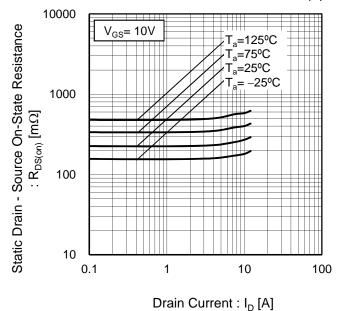


Fig.16 Drain Current Derating Curve

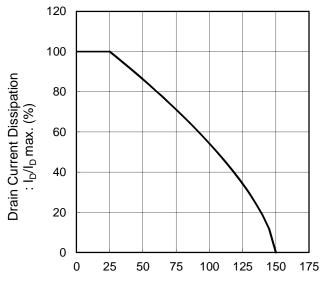
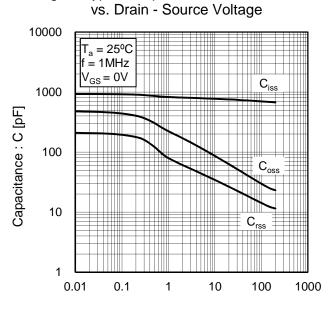
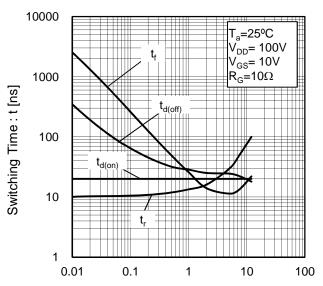


Fig.17 Typical Capacitance



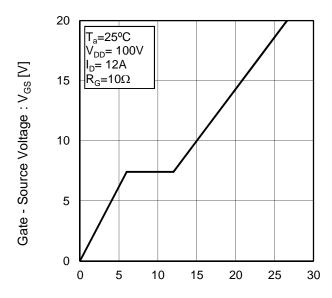
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics

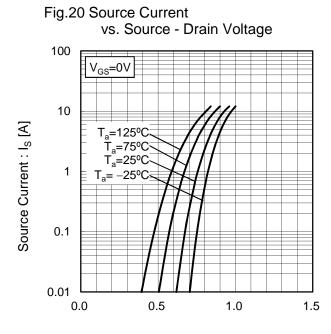


Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]



Source Current : I_S [A]

Fig21 Reverse Recovery Time

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

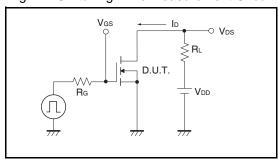


Fig.2-1 Gate Charge Measurement Circuit

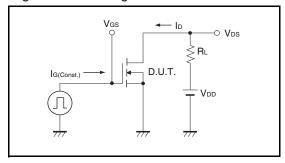


Fig.3-1 Avalanche Measurement Circuit

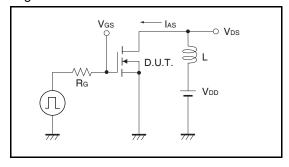


Fig.1-2 Switching Waveforms

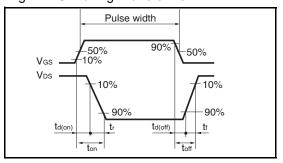


Fig.2-2 Gate Charge Waveform

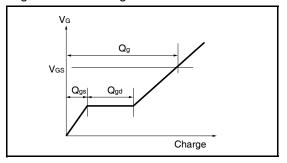
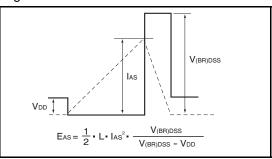
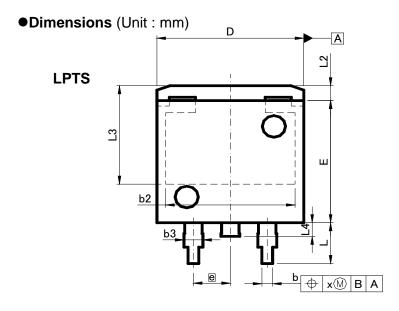
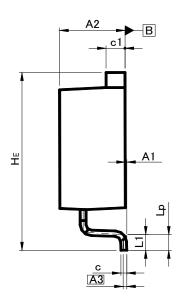
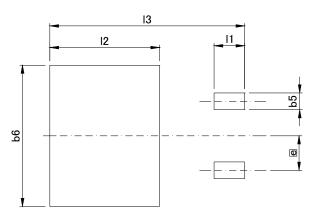


Fig.3-2 Avalanche Waveform









Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.	10
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0	143
L3	7.	25	0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM	MILIM	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b5	ı	1.23	ı	0.049
b6	İ	10.40	İ	0.409
11	-	2.10	-	0.083
12	=	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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